SCAS333D - DECEMBER 1992 - REVISED OCTOBER 1998

	Skew, Low Pulse Skew for button and Clock-Generation		PACKAGE P VIEW)
••			U 20 VCC
TTL-Comparison	tible Inputs and Outputs	1G 🛛 2	19 🛛 1Y1
 Distributes 	One Clock Input to Eight	2G [3	18 1Y2
Outputs		A 🛛 4	17 GND
• Distributed	V _{CC} and Ground Pins Reduce	P0 5	16 🛛 1Y3
Switching N		P1 6	15 🛛 1Y4
High-Drive (Outputs (–48-mA I _{OH} ,		14 🛛 GND
48-mA IOI)		2Y4 [8	13 2Y1
	-Art <i>EPIC-</i> II <i>B</i> ™ BiCMOS Design	2Y3 [9	12 2Y2
	y Reduces Power Dissipation	GND [10	11] GND
	Options Include Plastic ne (DW) Packages		

description

The CDC341 is a high-performance clock-driver circuit that distributes one (A) input signal to eight (Y) outputs with minimum skew for clock distribution. Through the use of the control pins (1G and 2G), the outputs can be placed in a low state regardless of the A input.

The propagation delays are adjusted at the factory using the P0 and P1 pins. These pins are not intended for customer use and should be strapped to GND.

The CDC341 is characterized for operation from 0°C to 70°C.

	INPUTS		OUTPUTS				
1G	2G	Α	1Y1-1Y4	2Y1-2Y4			
Х	Х	L	L	L			
L	L	Н	L	L			
L	Н	Н	L	Н			
н	L	Н	н	L			
н	Н	Н	н	Н			

FUNCTION TABLE



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

EPIC-IIB is a trademark of Texas Instruments Incorporated.

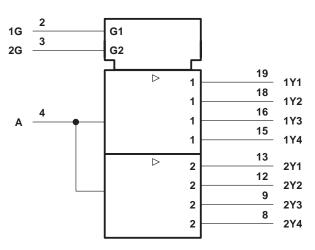
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



Copyright © 1998, Texas Instruments Incorporated

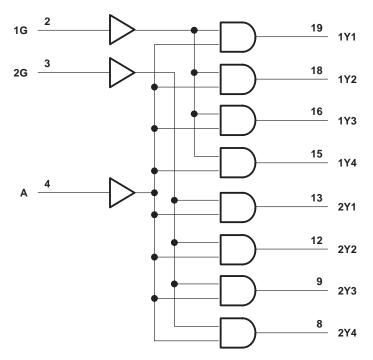
SCAS333D - DECEMBER 1992 - REVISED OCTOBER 1998

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





SCAS333D - DECEMBER 1992 - REVISED OCTOBER 1998

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1) Voltage range applied to any output in the high state or power-off state,	
V_{O} (see Note 1)	$-0.5 V to V_{0.0} \pm 0.5 V$
Current into any output in the low state, I _O	00
Input clamp current, I_{IK} ($V_I < 0$)	
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2)	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

 The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
Vcc	Supply voltage		4.75	5.25	V
VIH	High-level input voltage		2		V
VIL	Low-level input voltage			0.8	V
VI	Input voltage		0	VCC	V
ЮН	High-level output current			-48	mA
IOL	Low-level output current			48	mA
£	Input clock frequency	One output bank loaded		80	MHz
fclock	input clock nequency	Both output banks loaded		40	IVITIZ
TA	Operating free-air temperature		0	70	°C

NOTE 3: Unused pins (input or I/O) must be held high or low.



SCAS333D - DECEMBER 1992 - REVISED OCTOBER 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	т	TEST CONDITIONS				;	MIN	MAX	UNIT
FARAMETER	· · · · · · · · · · · · · · · · · · ·					MAX		IVIAA	UNIT
VIK	V _{CC} = 4.75 V,	lı = -18 mA				-1.2		-1.2	V
	V _{CC} = 4.75 V,	I _{OH} = – 3 mA		2.5			2.5		
VOH	$V_{CC} = 5 V,$	I _{OH} = – 3 mA		3			3		V
	V _{CC} = 4.75 V,	I _{OH} = - 48 mA		2			2		
V _{OL}	V _{CC} = 4.75 V,	I _{OL} = 48 mA						0.5	V
lj	V _{CC} = 5.25 V,	$V_I = V_{CC} \text{ or } GND$				±1		±1	μΑ
10‡	V _{CC} = 5.25 V,	V _O = 2.5 V		-50	-100	-200	-50	-200	mA
laa	$V_{CC} = 5.25 V,$		Outputs high		2			3.5	mA
Icc	$V_{I} = V_{CC} \text{ or } GND$	-	Outputs low		24			33	IIIA
Ci	V _I = 2.5 V or 0.5 V				3				pF

[†] All typical values are at $V_{CC} = 5 V$.

[‡]Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

switching characteristics, $C_L = 50 \text{ pF}$ (see Figures 1 and 2)

PARAMETER	FROM		V _{CC} = 5 V, T _A = 25°C			V _{CC} = 4.75 T _A = 0°	UNIT	
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	
^t PLH	А	V	3.5		4.5	3.1	4.9	ns
^t PHL	A	Ι	3.5		4.3	3.1	4.9	115
^t PLH	G	V	2		3.8	2	4	ns
^t PHL	9	'	2		3.8	2	4	115
^t sk(o)				0.3	0.5		0.6	
^t sk(p)	А	Y		0.6	0.8		0.9	ns
^t sk(pr)					1		1	
tr	А	Y					1.5	ns
t _f	А	Y					1.5	ns

t_{pd} performance information relative to V_{CC} and temperature variation (see Note 4)

Dt _{PLH(TA)} †	Temperature drift of tPLH from 0°C to 70°C	-41 ps/10°C
DtPHL(TA) [†]	Temperature drift of tPHL from 0°C to 70°C	−52 ps/10°C
Dt _{PLH(VCC)} ‡	V _{CC} drift of t _{PLH} from 4.75 V to 5.25 V	28 ps/100 mV
Dt _{PHL(VCC)} ‡§	V _{CC} drift of t _{PHL} from 4.75 V to 5.25 V	20 ps/100 mV

[†] Virtually independent of V_{CC}

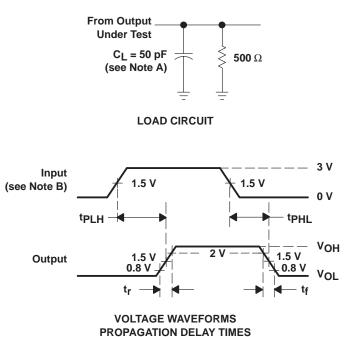
[‡] Virtually independent of temperature

NOTE 4: The data extracted is from a wide range of characterization material.



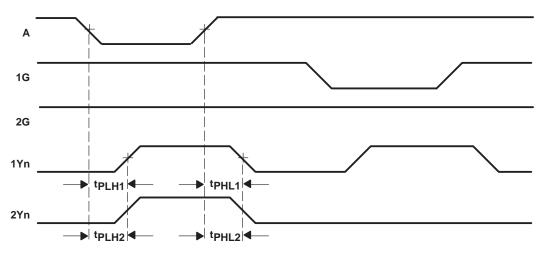
SCAS333D - DECEMBER 1992 - REVISED OCTOBER 1998

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 - B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_Q = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.

Figure 1. Load Circuit and Voltage Waveforms



- NOTES: A. Output skew, $t_{Sk(0)}$, is calculated as the greater of:
 - The difference between the fastest and slowest of t_{PLHn} (n = 1, 2) The difference between the fastest and slowest of t_{PHLn} (n = 1, 2)

 - B. Pulse skew, $t_{sk(p)}$, is calculated as the greater of $|t_{PLHn} t_{PHLn}|$ (n = 1, 2).
 - C. Process skew, $t_{sk(pr)}$, is calculated as the greater of:
 - The difference between the fastest and slowest of tpLHn (n = 1, 2) across multiple devices under identical operating conditions
 - The difference between the fastest and slowest of tPHLn (n = 1, 2) across multiple devices under identical operating conditions

Figure 2. Waveforms for Calculation of tsk(o), tsk(p), tsk(pr)



PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CDC341DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC341	Samples
CDC341DWG4	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC341	Samples
CDC341DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC341	Samples
CDC341DWRG4	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	CDC341	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and



www.ti.com

10-Dec-2020

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

Texas Instruments

www.ti.com

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are	nominal
---------------------	---------

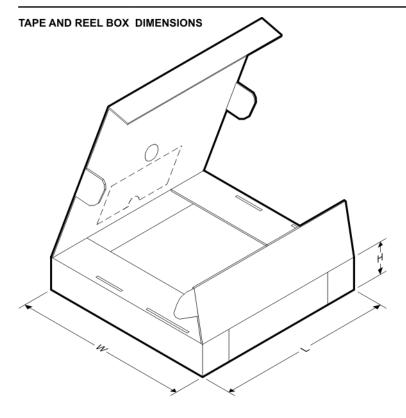
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDC341DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1



www.ti.com

PACKAGE MATERIALS INFORMATION

5-Jan-2022



*All dimensions are nominal

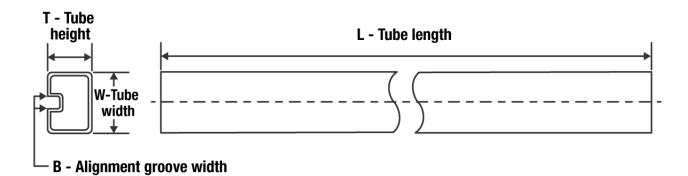
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC341DWR	SOIC	DW	20	2000	367.0	367.0	45.0



www.ti.com

5-Jan-2022

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
CDC341DW	DW	SOIC	20	25	507	12.83	5080	6.6
CDC341DWG4	DW	SOIC	20	25	507	12.83	5080	6.6

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2022, Texas Instruments Incorporated